PTO-1595	R SHEET U.S. DEPARTMENT OF COMMERCE
	Patent and Trademark Office
To the Honorable Commissioner of1023262	attached original documents or copy thereof.
1 Name of conveying party(ies):	2 Name and address of receiving party(ies):
Chao-Hsiang Yang Chun-Ming Su 12-18-22	Taiwan Semiconductor Manufacturing Co. Ltd. No. 121 Park Avenue 3 Science-Based Industrial Park Hsin-Chu, Taiwan, R.O.C.
3 Nature of conveyance: ■ Assignment □ Merger	Science-Based Industrial Park Hsin-Chu, Taiwan, R.O.C. Additional name(s) & address(es) attached □ Yes No
☐ Security Agreement ☐ Change of Name	
☐ Other: Execution Date: November 16, 2002	
4 Application number(s) or patent number(s):	
If this document is being filed together with a new application	on, the execution date of the application is: 11-16-02
A. Patent Application No(s).	B. Patent No(s)
10,323350	
Additional numbers	l attached? □ Yes ⊠ No
5 Name and address of party to whom correspondence concerning document should be mailed:	6 Total number of applications and patents involved: 1
RANDY W. TUNG	7 Total fee (37 CFR 3.41) \$40.00
Tung & Associates 838 W. Long Lake Road Suite 120	□ Enclosed
Bloomfield Hills, Michigan 48302	■ Authorized to charge credit card (w/filing fee)
02 RMEBRAHT 00000062 10323350	8 Deposit Account Number: 50-0484
21 40.00 €P	(Attach duplicate copy of this page if paying by deposit account)
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9 Statement and signature.	1
To the best of my knowledge and belief, the foregoing inforthe original document.	mation is true and correct and any attached copy is a true copy of
Randy W. Tung	
Name of Person Signing Signature Registration No. 31,311	Date
Total nur	mber of pages including cover sheet, attachments, and document : 3

Mail documents to be recorded with required cover sheet information to Commissioner of Patents & Trademarks, Box Assignments Washington, D.C. 20231 67,200-862 2001-1415/1526 2002-0416

ASSIGNMENT

WHEREAS, we, CHAO-HSIANG YANG and CHUN-MING SU have invented

certain improvements in

METHOD OF FORMING A METAL FUSE ON SEMICONDUCTOR DEVICES

for which we are about to make application for Letters Patent of the United States; and

WHEREAS, TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD. of

No. 121, Park Avenue 3, Science-Based Industrial Park, Hsin-Chu, Taiwan, R.O.C, is desirous of

acquiring the entire right, title and interest in and to said invention;

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and other good and

valuable consideration, the receipt of which is hereby acknowledged, we, <u>CHAO-HSIANG YANG</u>

and CHUN-MING SU, by these presents, do hereby sell, assign and transfer unto the said

corporation and its assigns, for the territory of the United States of America and all foreign countries,

the entire right, title and interest, including all priority rights under the International Convention

associated with each country of the Union, in and to said invention as described in the patent

application executed by us on the 16th and 25th day of November, 2002, preparatory to

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PATENT

REEL: 013609 FRAME: 0327

obtaining Letters Patent of the United States thereon, and in and to said application and any Letters

Patent that may be granted in pursuance of said application and any divisional, continuation or

continuation-in-part application thereof, and in and to any reissue of any such patent, and in and to

any patent applications which may be filed on said invention in countries foreign to the United States

and any Letters Patent granted thereon.

We further authorize said corporation to apply for foreign patents on said invention

in its own name or through its designees, including subsidiaries, related companies or assignees,

under the International Convention or otherwise, and we further agree to execute all papers,

including those required for the United States and foreign applications, and to perform such other

proper acts as said corporation or its designees the rights herein assigned.

Char-Hsiang Yang Chun-Ming Su CHAO-HSIANG YANG CHUN-MING SU

RECORDED: 12/18/2002

TUNG & ASSOCIATES 838 W. Long Lake Road Suite 120 Bloomfield Hills, Michigan 48302

PATENT REEL: 013609 FRAME: 0328